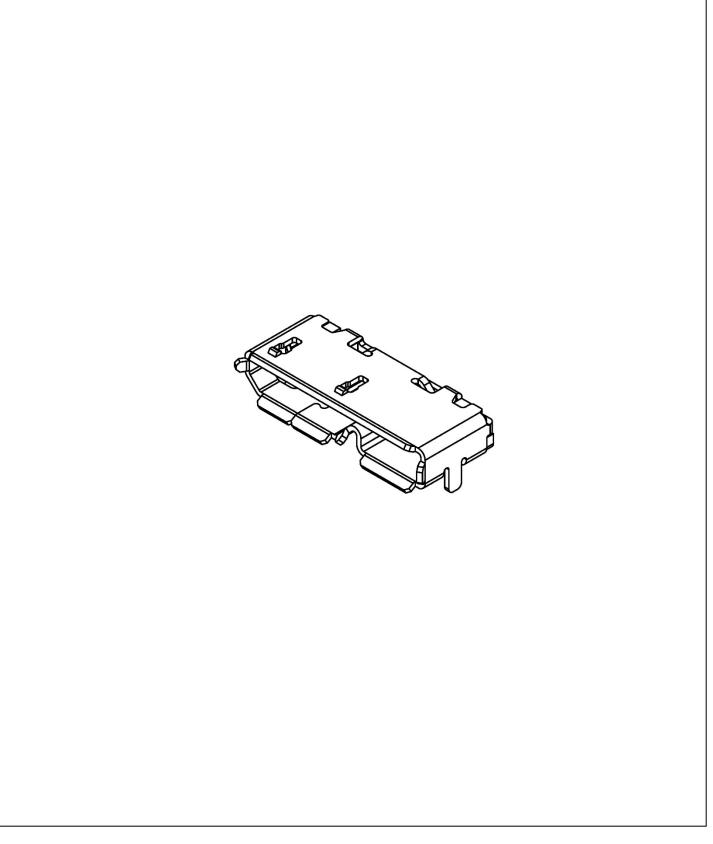
| Part Number | USB3110 | | Rev | | D | Date | 14/12/16 |
|------------------------|--|----------|-----|---------|----|----------|----------|
| Product Description | USB3.0 Micro Receptacle, Type B, SMT, Horizontal, 10 Pin, Bottom mount, with Outer Shell Stakes | | | | | Page | 1 |
| Doc Number | USB3110 | Prepared | СМ | Checked | DR | Approved | VJ |





| Part Number | USB3110 | | Rev | | D | Date | 14/12/16 |
|------------------------|--|----------|-----|---------|----|----------|----------|
| Product Description | USB3.0 Micro Receptacle, Type B, SMT, Horizontal, 10 Pin, Bottom mount, with Outer Shell Stakes | | | | | Page | 2 |
| Doc Number | USB3110 | Prepared | СМ | Checked | DR | Approved | VJ |

1.0 SCOPE.

This specification covers performance, tests and quality requirements for the USB3.0 Receptacle USB3110 (Type B, 10-Pin, SMT, Horizontal).

2.0 PRODUCT NAME AND PART NUMBER.

USB3.0 Receptacle, 10-Pin, Type B: USB3110.

3.0 PRODUCT SHAPE, DIMENSIONS AND MATERIAL.

Please refer to drawings.

4.0 RATINGS.

| 4.1 Current rating | Signal Mode - 1.0A AC/DC All Pins | | | |
|---------------------------------|---|--|--|--|
| | Power Mode - | | | |
| | Signal Pins 2,3,4,6,7,8 & 9 at 0.5A AC/DC & | | | |
| | Power Pins 1 & 5 at 1.8A AC/DC | | | |
| 4.2 Voltage rating | 30V AC/DC | | | |
| 4.3 Operating Temperature Range | -30°C to +85°C | | | |

5.0 TEST AND MEASUREMENT CONDITIONS.

Product is designed to meet electrical, mechanical and environmental performance requirements specified in Paragraph 6.0. All tests are performed in ambient conditions unless otherwise specified.

6.0 PERFORMANCE.

| Item | Test Condition | Requirement |
|------------------------|--|--|
| Examination of Product | Visual, dimensional and functional per applicable quality inspection plan. | Product shall meet requirements of applicable product drawing and specification. |



| Part Number | USB3110 | | Rev | | D | Date | 14/12/16 |
|------------------------|--|----------|-----|---------|------|----------|----------|
| Product Description | USB3.0 Micro Receptacle, Type B, SMT, Horizontal, 10 Pin, Bottom mount, with Outer Shell Stakes | | | | Page | 3 | |
| Doc Number | USB3110 | Prepared | СМ | Checked | DR | Approved | VJ |

6.1 Electrical Performance.

| Item | Test Condition | Requirement |
|---|---|---------------------------|
| Low-signal Level Contact Resistance | When measured at 20mV maximum open circuit at 100mA. Mated test contacts must be in a connector housing. 10mΩ maximum change for post-test LLCR. In accordance with EIA-364-23. | 30 mΩ Max. |
| Insulation Resistance | Mate/Un-mate connectors, apply 100V DC for 1 minute between adjacent terminal or ground. In accordance with EIA-364-21. | 1000MΩ Min. |
| Dielectric Withstanding Voltage The dielectric must withstand 100VAC one minute at sea level. In accordance with EIA-364-20. | | No breakdown. |
| Temperature Rise | Mate connector and measure the temperature rise of contact when the maximum AC rated current is passed. In accordance with EIA-364-70. | 30°C Max. change allowed. |

6.2 Mechanical Performance.

| Item | Test Condition | Requirement |
|-------------------------|--|---|
| Mating / Unmating Force | Mate / un-mated at a rate of 12.5 mm per minute. In accordance with EIA-364-13. | Initial: Mating force: 35N Max. Un-mating force: 10N Min. Final (after 10k cycles): Mating force: 35N Max. Un-mating force: 8N Min. |
| Durability | Cycle rate of 200 cycles per hour (manually) Cycle rate of 500max cycles per hour (automatically). In accordance with EIA-364-09. | 10,000 cycles. Appearance: No breakdown Mating force: 35N maximum. Un-mating force: 10N minimum. LLCR: 40 milliohm Max. |
| Vibration | No discontinuities of 1µS or longer duration when mated USB connectors are subjected to 3.10 GRMS.15 minutes in each of three mutually perpendicular planes. In accordance with EIA-364-28, Test condition VII, Test letter D. | Appearance: No Damage Discontinuity: 1.0μ second Max. |



| Part Number | USB3110 | | Rev | | D | Date | 14/12/16 |
|------------------------|--|----------|-----|---------|----|----------|----------|
| Product Description | USB3.0 Micro Receptacle, Type B, SMT, Horizontal, 10 Pin, Bottom mount, with Outer Shell Stakes | | | | | Page | 4 |
| Doc Number | USB3110 | Prepared | СМ | Checked | DR | Approved | VJ |

| Item | Test Condition | Requirement |
|------------------|---|---|
| Mechanical Shock | Mated USB connectors are subjected to 11ms duration 30Gs half-sine shock pules. Three shocks in each direction applied along three mutually perpendicular planes for 18 shocks. In accordance with EIA-364-27. Test Condition H | Appearance: No Damage Discontinuity: 1.0µ second Max |

6.3 Environmental Performance and Others.

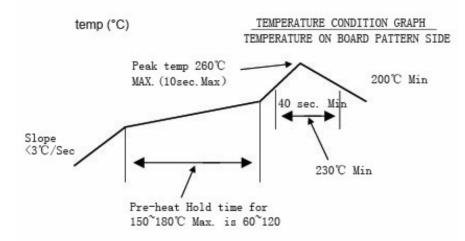
| Item | Test Condition | Requirement |
|--|---|---|
| Thermal Shock | 10 Cycles –55°C and +85°C. In accordance with EIA-364-32. Test Condition I | Appearance: No Damage Contact Resistance: 10 mΩ Change allow. |
| Cyclic Temperature & Humidity | Cycle the connector or socket between 25 °C \pm 3 °C at 80 % \pm 3% RH and 65 °C \pm 3 °C at 50 % \pm 3% RH. Ramp times should be 0.5 hour and dwell times should be 1.0 hour. Dwell times start when the temperature and humidity have stabilized within the specified levels. Perform 24 such cycles. In accordance with EIA-364-31 | Appearance: No Damage Contact Resistance: 10 mΩ change allowed. |
| Temperature Life | 105°C without applied voltage for 120 hours. In accordance with EIA-364-17 method A. | Appearance: No damage Contact Resistance: 10 mΩ change allowed. |
| Solderability | Dip solder-tails in flux then immerse in solder bath at 255+/- 5 °C up to 0.5 mm from the bottom of the housing for 5 seconds. In accordance with EIA-364-52 Category 2. | 95% of immersed area must show no voids, pin holes. |
| Resistance to Soldering Heat (Hand Soldering) | Solder iron method Solder temperature: 350 +/- 10 °C Immersion time: 3 +/- 1 second. However, excessive pressure shall not be applied to the terminal. | Without deformation of case or excessive looseness of the terminals (pin.) |
| Resistance to Soldering Heat (Reflow Soldering) (see also 6.4) | For procedures other than specified below, refer to IEC PUB. 68-2-20. Test Tb Method 1A or 2 Solder bath method Solder temperature: 260 +0/- 5 °C Immersion time: 10 +/- 1 second Thickness of P.C.B: 0.8 mm. In accordance with EIA-364-56 | Without deformation of case or excessive looseness of the terminals (pin.) (Apply to SMT parts only) |



| Part Number | USB3110 | | Rev | | D | Date | 14/12/16 |
|------------------------|--|----------|-----|---------|----|----------|----------|
| Product Description | USB3.0 Micro Receptacle, Type B, SMT, Horizontal, 10 Pin, Bottom mount, with Outer Shell Stakes | | | | | Page | 5 |
| Doc Number | USB3110 | Prepared | СМ | Checked | DR | Approved | VJ |

6.4 Infrared Reflow Condition

Fig. 1. Lead-free Process: Duration = 2 Times.





| Part Number | USB3110 | | Rev | | D | Date | 14/12/16 |
|------------------------|--|----------|-----|---------|----|----------|----------|
| Product Description | USB3.0 Micro Receptacle, Type B, SMT, Horizontal, 10 Pin, Bottom mount, with Outer Shell Stakes | | | | | Page | 6 |
| Doc Number | USB3110 | Prepared | СМ | Checked | DR | Approved | VJ |

7.0 PRODUCT QUALIFICATION AND TEST SEQUENCE

| | Test Group | | | | | | | | |
|---------------------------------------|------------|----------|-----|-----------|---------------|-----|-----|-----|-----|
| Test or Examination | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 |
| | | | | Tes | Test Sequence | | | | |
| Examination of Product | 1,3 | 1,1 0 | 1,6 | 1,7 | 1,6 | 1,4 | 1,4 | 1,3 | 1,3 |
| Low-signal Level Contact Resistance | | 2,9 | 2,5 | 2,4, 6 | 2,9 | 2,5 | | | |
| Dielectric Withstanding Voltage | | 3,8 | | | | | | | |
| Temperature rise | 2 | | | | | | | | |
| Mating / Unmating Forces | | 4,7 | | | | | | | |
| Durability | | 5 | | | | | | | |
| Vibration | | | 3 | | | | | | |
| Mechanical shock | | | 4 | | | | | | |
| Cyclic temperature & Humidity | | | | 5 | | | | | |
| Temperature life | | 6 | | | | | | | |
| Thermal shock | | | | 3 | | | | | |
| Solder ability | | | | | | | 2 | | |
| Resistance to Soldering Heat (Wave) | | | | | | | | 2 | |
| Resistance to Soldering Heat (Hand) | | | | | | | | | 2 |
| Resistance to Soldering Heat (Reflow) | | | | | | | 3 | | |
| Sample Size | 5 | 5 | 5 | 5 | 5 | 5 | 5 | 5 | 5 |



| Part Number | USB3110 | | Rev | | D | Date | 14/12/16 |
|------------------------|--|----------|-----|---------|----|----------|----------|
| Product Description | USB3.0 Micro Receptacle, Type B, SMT, Horizontal, 10 Pin, Bottom mount, with Outer Shell Stakes | | | | | | 7 |
| Doc Number | USB3110 | Prepared | СМ | Checked | DR | Approved | VJ |

Revision details :-

| Revision | Information | Page | Release Date |
|----------|---|------|--------------|
| А | Specification released. | - | 15/06/11 |
| В | General Process Removed | 5 | 05/01/12 |
| С | Complete Revision | All | 17/09/12 |
| D | Changed Voltage Rating from 100V AC/DC to 30V AC/DC (In line with USB-IF spec) | 2 | 14/12/16 |

